## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re	U.S. Patent Application of	)
TACI	HIBANA et. al.	) }
Appli	cation Number: To be Assigned	)
Filed:	Concurrently Herewith	{
For:	HEAT SPREADER AND SEMICONDUCTOR DEVICE AND PACKAGE USING THE SAME	) ) )
Attor	ney Docket No. KOBE.0057	)

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

## **PRELIMINARY AMENDMENT**

Sir:

Prior to an examination on the merits, please amend the above-identified application as follows: